

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

Claim 1 (withdrawn) A metal mask for use with a circuit board (2) having an electrode (21) formed in a predetermined pattern to join an end portion of a lead member (6) thereto for applying a lead-free solder paste (30) to the electrode (21) of the predetermined pattern, the metal mask being characterized in that the metal mask has two openings (11a, 11b) formed at a position corresponding to the position of the electrode (21) on the circuit board (2) and arranged in a direction in which the lead member (6) is to extend from the electrode (21) toward other circuit, the two openings (11a, 11b) being each circular or elliptical in shape.

Claim 2 (withdrawn) A metal mask according to claim 1 wherein the two openings (11a, 11b) are each in the shape of an ellipse having a minor axis in said direction in which the lead member (6) is to extend.

Claim 3 (withdrawn) A metal mask according to claim 1 wherein the first (11a) of the two openings (11a, 11b) which is positioned closer to said end portion of the lead member (6) to be joined to the electrode (21) on the circuit board (2) is smaller than the other second opening

(11b) in area.

Claim 4 (withdrawn) A metal mask according to claim 3 wherein the area ratio of the first opening (11a) to the second opening (11b) is 1:1.5 to 1:3.

Claim 5 (withdrawn) A metal mask according to claim 1 wherein the two openings (11a, 11b) are so sized that opposite ends thereof in directions orthogonal to said direction in which the lead member (6) is to extend bulge out of the electrode (21) on the circuit board (2) toward the respective directions.

Claim 6 (withdrawn) A metal mask according to claim 5 wherein the opening (11b) of the two openings (11a, 11b) which is positioned toward said direction in which the lead member is to extend is so sized that an end thereof toward said direction in which the lead member is to extend bulges out of the electrode (21) on the circuit board (2) toward said same direction.

Claim 7 (withdrawn) A metal mask according to claim 1 wherein the two openings (11a, 11b) are in communication with each other at side portions thereof.

Claim 8 (currently amended) A lead-free solder paste printing method comprising placing a metal mask (1) on a circuit board (2) having an electrode (21) formed in a

predetermined pattern to join an end portion of a lead member (6), and moving a printing squeegee (4) along an upper surface of the metal mask (1) to thereby print a lead-free solder paste (30) on a surface of the electrode (21) on the circuit board (2), wherein the metal mask (1) has two openings (11a, 11b) having centers on a line extending longitudinally of the lead member (6) and formed at a position within a region corresponding to the ~~position of the~~ electrode (21) on the circuit board (2) to join the end portion of the lead member (6), ~~[[and]]~~ each having an elliptical non-circular shape, wherein the first (11a) of the two openings (11a, 11b) which is positioned closer to said end portion of the lead member (6) is smaller than the other second opening (11b) in area, and two lead-free solder paste patterns (30a, 30a) are printed on the electrode (21) by using the metal mask (1), the two solder paste patterns being arranged longitudinally of ~~in a direction in which the lead member (6) is to extend from the electrode (21) toward another circuit.~~

Claim 9 (original) A lead-free solder paste printing method according to claim 8 wherein the first (11a) of the two openings (11a, 11b) of the metal mask (1) which is positioned closer to said end portion of the lead member (6) to be joined to the electrode (21) on the circuit board (2) is smaller than the other second opening (11b) in area.

Claim 10 (previously presented) A lead-free solder paste printing method comprising placing a metal mask (1) on a circuit board (2) having an electrode (21) formed in a

predetermined pattern to join an end portion of a lead member (6), and moving a printing squeegee (4) along an upper surface of the metal mask (1) to thereby print a lead-free solder paste (30) on a surface of the electrode (21) on the circuit board (2), wherein the metal mask (1) has two openings (11a, 11b) formed at a position corresponding to the position of the electrode (21) on the circuit board (2) and each having an elliptical shape, and two lead-free solder paste patterns (30a, 30a) are printed on the electrode (21) by using the metal mask (1), the two solder paste patterns being arranged in a direction in which the lead member (6) is to extend from the electrode (21) toward another circuit,

wherein the first (11a) of the two openings (11a, 11b) of the metal mask (1) which is positioned closer to said end portion of the lead member (6) to be joined to the electrode (21) on the circuit board (2) is smaller than the other second opening (11b) in area, and

wherein the area ratio of the first opening (11a) of the metal mask (1) to the second opening (11b) thereof is 1:1.5 to 1:3.

Claim 11 (withdrawn) A lead-free solder paste printing method according to claim 8 wherein the two openings (11a, 11b) of the metal mask (1) are so sized that opposite ends thereof in directions orthogonal to said direction in which the lead member (6) is to extend bulge out of the electrode (21) on the circuit board (2) toward the respective directions.

Claim 12 (withdrawn) A lead-free solder paste printing method according to claim 11 wherein the opening (11b) of the two openings (11a, 11b) of the metal mask (1) which opening is positioned toward said direction in which the lead member is to extend is so sized that an end thereof toward said direction in which the lead member is to extend bulges out of the electrode (21) on the circuit board (2) toward said same direction.

Claim 13 (withdrawn) A lead-free solder paste printing method according to claim 8 wherein the lead-free solder paste (30) comprises a solder consisting mainly of tin and containing silver, or a solder consisting mainly of tin and containing silver and copper.

Claim 14 (previously presented) A lead-free solder paste printing method according to claim 8, wherein each of the openings (11a, 11b) has a minor axis in a direction in which the lead member (6) is to extend from the electrode.